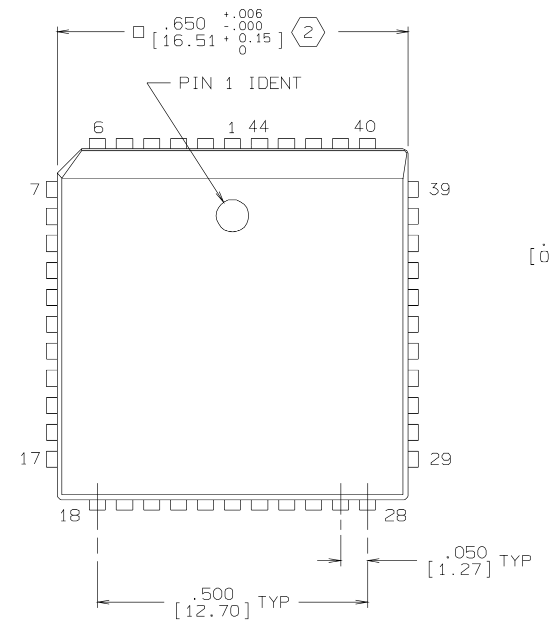
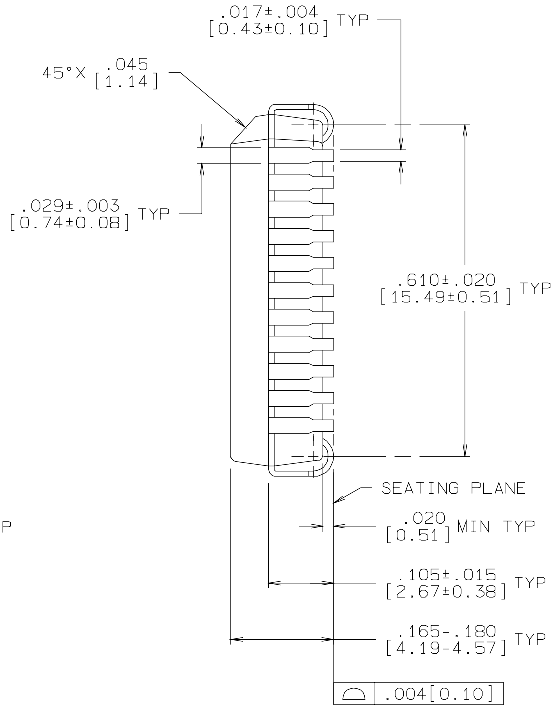
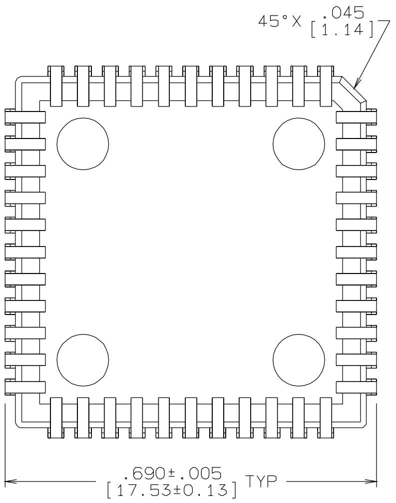
REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
J	REVISE & REDRAW PER STD FORMAT	09323	09/18/92	TL/SL
K	ADD COPLANARITY & SEATING PLANE; CONVERT LIMIT DIM'S TO NOM±TOL; NOTE 3: VARIATION WAS AD.	10034	12/03/93	MS/







CONTROLLING DIMENSION: INCH

MIL/AERO CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH: 200 MICROINCHES / 5.08 MICROMETERS MINIMUM SOLDER THICKNESS PER SIDE ON COPPER (Cu).
2. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM ALLOWABLE MOLD PROTRUSION .010 IN / 0.25 mm PER SIDE.
3. REFERENCE JEDEC REGISTRATION MO-047, VARIATION AC, DATED 5/90.

APPROVALS	DATE
DRAWN T. LEQUANG	09/16/92
DFTG. CHK.	
ENGR. CHK.	
APPROVAL	

PROJECTION

INCH [MM]

NATIONAL SEMICONDUCTOR CORPORATION
2900 Semiconductor Drive, Santa Clara, CA 95052-8090

PLASTIC CHIP CARRIER,
SQ, .050 LD PITCH,
44 LEAD

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	MKT-V44A	K

DO NOT SCALE DRAWING | SHEET 1 OF 1